



# *Simulation of Semiconductor Devices and Processes*

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# *Simulation of Semiconductor Devices and Processes*

# PREFACE

This conference was initiated by the rapidly growing interest in the field of semiconductor simulation prompted by the strong drive towards VLSI devices and circuits. This trend has called into question some of the traditional physical formulations of device operation and this is reflected in some of the keynote papers included herein.

The same trend has increased the interdependence of device simulation and the modelling of the technological processing used in their fabrication. For this reason we have covered both these topics in the proceedings, Section I being devoted to Device Modelling and including contributions ranging from reviews of the physical bases of the topic to the latest attempts to obtain efficient and robust 2-dimensional steady-state programs and to applications, including high frequency bipolars, microwave devices, high voltage MOSTs and Schottky devices. Section II is devoted to Process Simulation and following a review of current status includes contributions on the modelling of Oxidation, Impurity Diffusion in Polysilicon Sputtering Etching and an application to Multilayer VLSI structures.

The proceedings are printed from direct lithographs of authors manuscripts and the editors cannot accept any responsibilities for any inaccuracies, comments or opinions expressed in the papers.

Finally we would like to thank the authors for their efforts and co-operation in making the conference possible.

K. Board

D.R.J. Owen

Swansea, June 1984.

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**TWO-DIMENSIONAL TRANSIENT SIMULATION  
OF SEMICONDUCTOR DEVICES COUPLED  
TO AN EXTERNAL CIRCUIT**

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SUMMARY

In many practical situations of numerical semiconductor device simulation, especially in transient switching processes, a realistic analysis should take into account the interaction between the analysed device and the environment it is embedded in. The contact voltages can then no longer be considered, as is usually done, as "a priori" known boundary conditions for the basic partial differential equations (p.d.e.) describing the transport phenomena. They must rather be adjusted to satisfy the  $N$  (for an  $(N+1)$ -terminal device) nonlinear equations of the external circuit. As the resolution algorithm influences directly the number of expensive numerical solutions of the p.d.e., it must be chosen very carefully.

The iterative algorithm proposed in this paper is the sequential  $(N+1)$ -point secant method which essentially replaces the real current versus bias dependency by a linear relationship using the  $N+1$  most recent approximations of the applied voltages and the corresponding currents. Each iteration requires only one resolution of the p.d.e., whereas, for example, a discrete Newton iteration costs  $N+1$  times more. The method is able to handle efficiently resistive, reactive and nonlinear -analytically or even numerically modelled- components connected to the device under study. It is suitable for steady state and transient simulations in two or three space dimensions. It can be implemented without too much difficulty into existing device simulators, regardless of the particular numerical method used to solve the p.d.e. The asymptotic convergence rate of the secant method is superlinear and remains reasonably high for moderate values of  $N$  but, unfortunately, no theoretical guarantee of convergence can be given. Practical experience showed, however, that the method gives good results and the required precision was usually reached in 3 to 6 iterations.

The simulations of the turn-off of a gate controlled switch illustrates the use of the method. The impedances in gate and anode circuits definitely influence the observed current and voltage waveforms and may not be neglected.

## 1. INTRODUCTION

Since the first paper on numerical simulation of semiconductors devices, in 1964 [1], considerable effort has been and is being devoted to the improvement of existing methods or to the development of new, more powerful numerical techniques. Numerous publications witness of the progress realized in this area. From simplified 1D steady state problems, the application field has been widened to include 2D and even 3D, static and transient calculations, taking into account most of the relevant physical mechanisms through sophisticated physical models [e.g. 2-3].

Much less attention has, however, so far been paid to the problem of the interaction between the simulated device and the external circuit it is connected to. The basic partial differential equations (p.d.e.) describing the transport physics are commonly considered as a boundary value problem, where, at the metallic contacts, the carrier densities are fixed and the electric potential takes "a priori" known values, according to the prescribed bias conditions. The numerical resolution of the p.d.e. yields the distributions of internal variables such as free carrier concentrations, potential and current densities. After integration of the carrier flux, the terminal currents are obtained for given voltages. This corresponds to devices operating under ideal voltage sources and is often sufficient to yield useful simulation results. There are, however, many situations, where the interaction with a nonideal external circuit becomes essential for the device operation and can no longer be neglected. This is true for many switching processes, such as the forced turn-off of gate controlled power rectifiers. In the beginning of the switching process, the load impedance acts as a current source and keeps the anode current constant during the storage period. Afterwards, when the device impedance rises, the anode voltage increases sharply during the fall period of the anode current. Hence, at any moment, anode current and bias result from a balance between the gate controlled switch and the anode load circuit. The bias conditions are no longer "a priori" known, but must be adjusted to satisfy the nonlinear equations of the external circuit. The resolution algorithm for this apparently simple problem must be chosen very carefully, because it will require more or less, expensive numerical solutions of the p.d.e.

Already in 1977, Turgeon and Navon [4] presented simulation results of bipolar transistor switching with a reactive load, but little information was given about

the underlying algorithm. The approach developed by Mock [5-6] is attractive because it does not require any iterations for the circuit equations, but it is strongly related to the specific way the p.d.e. are solved. Recently, Grossmann and Hargrove [7] described a method where the circuit equations are inserted directly into the discretized p.d.e. and solved together with them. Once again, no additional iterative loop is necessary for the circuit equations, but a possible drawback is that the contact currents are evaluated by flux integration through a surface very close to the contact and hence laying in a heavily doped neutral region. In such regions, it is difficult to calculate accurately the current densities and, consequently, the terminal currents [8], in spite of highly accurate carrier densities and electric potential. Tomizawa et al. [9] used the discrete Newton's method to solve the circuit equations iteratively. This approach will be considered more in detail in section 3, because it has many similarities with our method which is based upon the sequential  $(N+1)$  - point algorithm. It allows to handle linear -static or dynamic- or nonlinear loads, described either analytically or even numerically. In the following presentation, only the former situation is considered, but the same reasoning applies to several interconnected, numerically modelled semiconductor devices. In that case, each device is treated separately within every iteration cycle.

In the following section 2, the problem to be solved is stated in a fairly general way. The sequential  $(N+1)$ -point secant method is described in section 3. It is compared to the related discrete Newton's method and basic theoretical convergence results are highlighted. The practical implementation of the method into an existing device simulation program is considered in section 4. The simulation of the turn-off of a gate controlled switch, presented in section 5, illustrates the use of the method for resistive circuit conditions and gives insight into the device internal phenomena during the switching. Section 6 concludes the present study.

## 2. STATEMENT OF THE PROBLEM

Let us consider a semiconductor device with  $N+1$  metallic contacts, where  $N$  usually ranges from 1 to 3. One contact is grounded without loss of generality and the others are numbered from 1 to  $N$ . Figure 1 is a sketch of the analysed system composed of a semiconductor device and the external circuit.

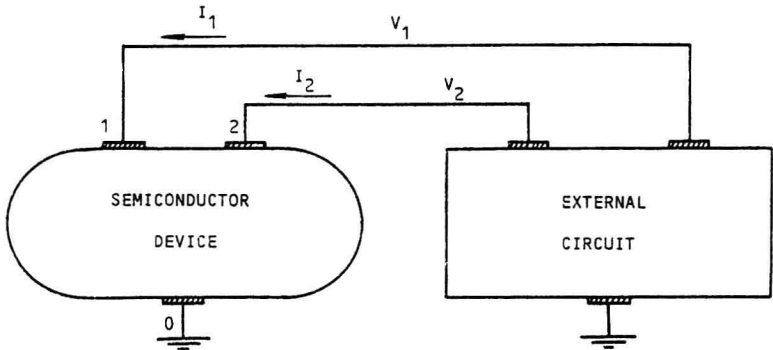


Fig.1 : Schematic representation of the analysed system ( $N=2$ ).

For the semiconductor device, the current vs. voltage relationship can formally be written as :

$$\underline{I} = \underline{f}(\underline{V}) \quad (1)$$

where  $\underline{I} = [I_1 \dots I_N]^t$ ,  $\underline{V} = [V_1 \dots V_N]^t$  and  $\underline{f} = [f_1 \dots f_N]^t$ . Equation (1) must, however, not be taken as an explicitly given relationship. It rather is a symbolic representation of the complex sequence of operations necessary for the numerical simulation of an electronic component. The major part is the numerical resolution of the basic p.d.e., i.e. Poisson's equation and the carrier conservation laws, for given bias conditions  $\underline{V}$ . The specific method used to solve this boundary value problem (by finite elements or finite differences or any other approach) is not relevant at the present time. Once the internal distributions of the carrier densities and the potential are known, the current densities can be calculated. Integration of the current flow through surfaces separating the contacts, yields then the corresponding terminal currents.

Equation (1) still holds for transient calculations, but it has to be interpreted as a local relationship in time, assuming that partial time derivatives in the basic p.d.e. are expressed by discrete formulas and that the values of the dependent variables are known for all previous time instants.

The external circuit must satisfy a similar relationship :

$$\underline{I} = -\underline{g}(\underline{V}) \quad (2)$$

Normally, the external circuit is very simple, because the interest is focused upon the semiconductor device and the physical phenomena occurring within it. For instance, with resistive loads, we have :

$$g_i(\underline{V}) = g_i(V_i) = (V_i - E_i)/R_i \quad i = 1 \dots N \quad (3)$$

where  $R_i$  and  $E_i$  are respectively, the load resistance and the  $i$  voltage source connected to the  $i$ th contact. The external circuit might, however, also be more complicated and contain dynamic or nonlinear elements described by analytical or even numerical models.

The question is now to find the bias conditions  $\underline{V}$  such that the currents leaving the external circuit equal the currents entering the semiconductor :

$$\underline{f}(\underline{V}) + \underline{g}(\underline{V}) = 0 \quad (4)$$

This apparently simple nonlinear problem requires a careful selection of the resolution algorithm in accordance with special features. The number of unknowns  $N$  is very small, but the function evaluation  $\underline{f} + \underline{g}$  is very expensive. Furthermore, no explicit expressions of the derivatives can be given, but they can be estimated through discrete approximations. Consequently, the resolution method should converge very quickly, and the number of evaluations of the function (and the derivatives) per iteration should be as small as possible.

### 3. THE SEQUENTIAL (N+1)-POINT SECANT METHOD

To solve equation (4), one might think of Newton's iterative method :

$$\underline{d} = -(\underline{J}_f + \underline{J}_g)^{-1} (\underline{f}(\underline{V}) + \underline{g}(\underline{V})) \quad (5)$$

$$\underline{V}_{\text{new}} = \underline{V} + \underline{d}$$

where the Jacobian matrix  $\underline{J} = \underline{J}_f + \underline{J}_g$  is the sum of the derivatives of  $\underline{f}$  and  $\underline{g}$  w.r.t. the components of  $\underline{V}$ . The latter are normally easily obtained, but no explicit formulas can be given for the former. Therefore,  $\underline{J}_f$  must be evaluated by other means. For instance, each component of  $\underline{V}$  can be increased individually by a small amount and the corresponding function values  $\underline{f}$  are used to approximate the derivatives by difference formulas. This discretized

Newton iteration has been successfully used by Tomizawa et al. [9], but it will have, in general, only a linear rate of convergence [10, p.186] and requires  $N+1$  function evaluations per iteration.

Another approach is given by the general secant method [10, p.189 ff.] which replaces the Jacobian matrix by a secant matrix obtained in the following way. The exact current vs. voltage dependency  $\underline{I} = f(\underline{V})$  is replaced by a linear relationship using the function values at  $N+1$  different points. Obviously, still  $N+1$  function evaluations are, in general, necessary, but, if the points are properly selected, a second order convergence rate can be reached.

A very interesting special case is the sequential  $(N+1)$ -point method [10, p.196], where the available function values at the  $N+1$  most recent approximations of  $\underline{V}$  are used to set up the secant matrix. Only one function evaluation is sufficient to find the improved approximation of  $\underline{V}$  and hence to finish off the iteration. As the method has also a superlinear convergence rate, it appears to be particularly well suited for the present application. Although the convergence rate decreases with  $N$ , it remains reasonably high for the values of  $N$  of practical interest : it is 1.62, 1.47 and 1.38 for  $N = 1, 2$  and 3 respectively [10, p.373]. Unfortunately, there is no theoretical guarantee of local convergence [10, p.379], but our experience showed that the method gives good results. A special problem is due to the fact that the secant matrix becomes singular, if the  $N+1$  last approximations of  $\underline{V}$  are not in general position in  $R^N$ , i.e. if the  $N$  vectors issued from one of these points to the others are linearly dependent. This problem is however rarely encountered and can easily be dealt with by keeping the old secant matrix until the points are again in general position. The algorithm degenerates hence temporarily into a parallel chord method.

#### 4. PRACTICAL IMPLEMENTATION

The procedure described in the previous section can be implemented into existing semiconductor device simulators without too much difficulty, independently of the particular numerical method used to solve the p.d.e. The method is suitable for steady state and transient calculations in two or three space dimensions, regardless of the internal resolution algorithm.

We have introduced the method into our 2D simulation program based upon a generalized finite difference discre-

tization scheme which handles combined triangular and rectangular grids [11]. The original code has been extended to include the time discretization, using a first order implicit predictor-corrector scheme [12]. The time step is adjusted automatically to achieve a constant prescribed local truncation error. The discrete equations are solved by a coupled resolution approach, based upon a full Newton linearization. The system matrix is assembled efficiently by a node by node technique which avoids multiple evaluation of the same quantities [11-12]. The resolution of the linear system is carried out using a successive line overrelaxation (SLOR) method which has been adapted to account for the particular matrix structure arising from irregular finite element like meshes. The line length is variable and the nonzero elemental  $3 \times 3$  blocks are irregularly distributed outside of the three main diagonals. These features can be handled without too much added complexity, and the SLOR method is economic in both memory requirements and CPU time.

If the secant method is used for the circuit equations, an additional outer iteration loop for the bias conditions is introduced. At the start of the simulation, the secant matrix is not yet defined, because only one function value is available. The matrix is initialized using the discrete Newton's method. The first iteration needs hence  $N+1$  function evaluations. This matrix is then kept unchanged for the following  $N-1$  iterations, until  $N+1$  function values are available. From then on, the secant matrix is updated at every iteration provided the resulting matrix is nonsingular, as explained in section 3.

The iteration loop is continued until convergence is reached, typically within 6 to 10 iterations for steady state calculations, depending on the accuracy of the initial guess. In the transient case, the required number of iterations ranges from 3 to 6, the former value corresponds to a smaller time step. It is not necessary to re-initialize the secant matrix when a new time step is started. The last matrix of the previous time step is simply taken over to the next one.

## 5. APPLICATION : THE TURN-OFF OF A GATE CONTROLLED SWITCH (GCS)

The forced switching-off of a gate controlled silicon rectifier is a typical application, where the interaction between the device and the load circuit is essential for the device operation. The considered structure of the gate controlled switch (GCS) is sketched in fig.2a. The doping profile along the x-axis is given in fig.2b, for



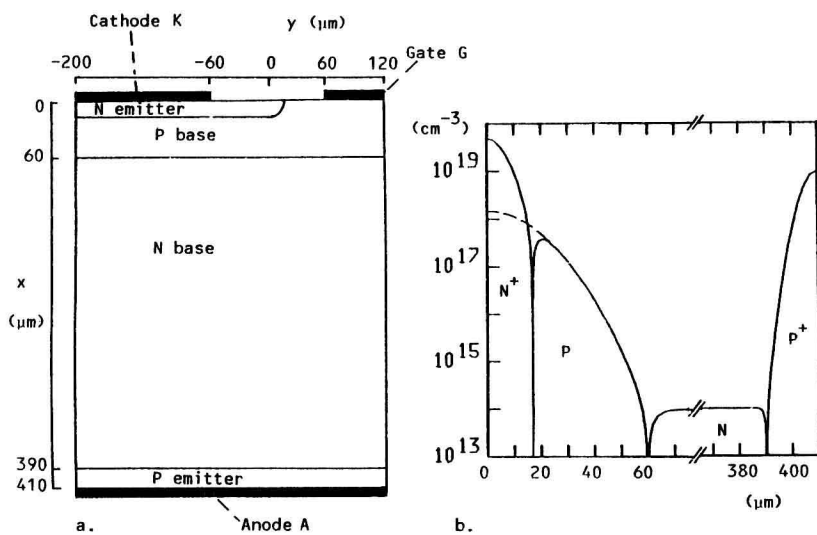


Fig.2 : Schematic representation of the GCS and the impurity distribution along the  $x$ -axis.

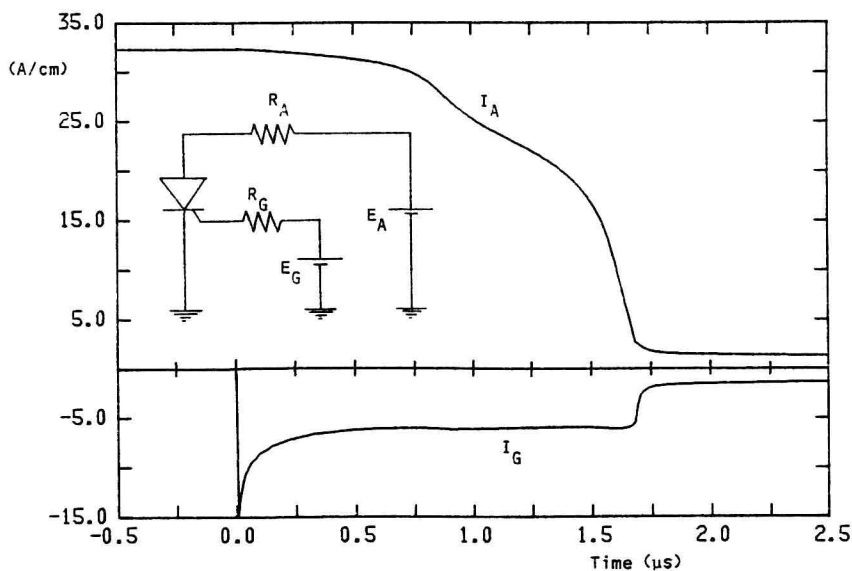


Fig.3 : Current wave forms for the simulated turn-off.

( $R_A=3\Omega\text{cm}$ ,  $R_G=0.5\Omega\text{cm}$ ,  $E_A=100\text{V}$ ,  $E_G=1.08\text{V}$  if  $t \leq 0$ ,  $E_G=-10\text{V}$  if  $t > 0$ )